

Title (en)

SHOE SOLE AND DEVICE FOR METHOD FOR FORMING SAID SOLE

Title (de)

SCHUHSOLE SOWIE VORRICHTUNG UND VERFAHREN ZUR FORMUNG DIESER SOHLE

Title (fr)

SEMELLE DE CHAUSSURE ET DISPOSITIF PERMETTANT LA MISE EN FORME D'UNE TELLE SEMELLE

Publication

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Application

**EP 08834983 A 20080901**

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Abstract (en)

[origin: WO2009044023A1] The invention relates to a shoe sole (1), in particular for practicing a sport, comprising a support (3) of a general form corresponding to the surface of at least a part of the base of the shoe and comprising at least one first layer in a thermoform material, characterised in comprising at least one second layer made from thermoform material, the second layer (6) partly covering the first layer (5) in order to leave at least one free zone (7, 8, 9, 10) at the level of the first layer (5), the material making up the first layer (5) having a thermoform temperature less than the thermoform temperature of the material making up the second layer (6). The invention further relates to a device for forming said sole.

IPC 8 full level

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